



## PCN / EOL Notification

**Product Change Notification Number:** HC093602

**Date\*:** September 9, 2009

**Title:** VIA Layer Change for T2526NxxxC and Transfer Wafer Fab Location from Heilbronn to Atmel Colorado Springs, CO

**Product Identification:**  
[See Attachment A](#)

**Reason for Change:**

☐ Design

☒ Manufacturing Location

☐ Processing

☐ Quality/Reliability

☐ Logistics

☒ Material

**Change Description:**

Changes to the VIA layer to improve bondability of the dies located close to the edge of the wafer – yield improvement. Process: BiCMOS. Wafer Fab: Transfer from Heilbronn to Atmel Colorado Springs, CO.

**Identification Method to Distinguish Change:**

The letter behind the part number changes from **N** to **S**.

New Part Number: T2526**S**xxxC-DDW

**Qualification Data:**

☒ available

☐ will be available in WW\_\_

☐ not applicable

**Samples:**

☒ available

☐ will be available in WW\_\_

☐ not applicable

**Quantifiable Impact on Quality & Reliability:**

No Impact on quality and reliability.

**Estimated Availability Date:** Available now

**Last Time Buy Date:** November 30, 2009

**Last Ship Date:** May 31, 2010

*\* All orders placed after the notification date are **non-cancellable** and **non-returnable (NCNR)**.*

**Atmel Contact:**

[pcnadm@atmel.com](mailto:pcnadm@atmel.com)

Atmel will deem this change accepted unless specific conditions of acceptance are provided in writing within 30 days from the date of this notice. All correspondence must be sent to the Atmel Contact e-mail address listed above.

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## Attachment A

| Old Part Number | New Part Number |
|-----------------|-----------------|
| T2526N030C-DDW  | T2526S030C-DDW  |
| T2526N033C-DDW  | T2526S033C-DDW  |
| T2526N036C-DDW  | T2526S036C-DDW  |
| T2526N037C-DDW  | T2526S037C-DDW  |
| T2526N038C-DDW  | T2526S038C-DDW  |
| T2526N040C-DDW  | T2526S040C-DDW  |
| T2526N056C-DDW  | T2526S056C-DDW  |
| T2526N130C-DDW  | T2526S130C-DDW  |
| T2526N138C-DDW  | T2526S138C-DDW  |
| T2526N140C-DDW  | T2526S140C-DDW  |
| T2526N156C-DDW  | T2526S156C-DDW  |
| T2526N230C-DDW  | T2526S230C-DDW  |
| T2526N236C-DDW  | T2526S236C-DDW  |
| T2526N238C-DDW  | T2526S238C-DDW  |
| T2526N240C-DDW  | T2526S240C-DDW  |
| T2526N256C-DDW  | T2526S256C-DDW  |
| T2526N330C-DDW  | T2526S330C-DDW  |
| T2526N333C-DDW  | T2526S333C-DDW  |
| T2526N336C-DDW  | T2526S336C-DDW  |
| T2526N337C-DDW  | T2526S337C-DDW  |
| T2526N338C-DDW  | T2526S338C-DDW  |
| T2526N340C-DDW  | T2526S340C-DDW  |
| T2526N356C-DDW  | T2526S356C-DDW  |
| T2526N630C-DDW  | T2526S630C-DDW  |
| T2526N636C-DDW  | T2526S636C-DDW  |
| T2526N638C-DDW  | T2526S638C-DDW  |
| T2526N640C-DDW  | T2526S640C-DDW  |
| T2526N656C-DDW  | T2526S656C-DDW  |
| T2526N730C-DDW  | T2526S730C-DDW  |
| T2526N733C-DDW  | T2526S733C-DDW  |
| T2526N736C-DDW  | T2526S736C-DDW  |
| T2526N737C-DDW  | T2526S737C-DDW  |
| T2526N738C-DDW  | T2526S738C-DDW  |
| T2526N740C-DDW  | T2526S740C-DDW  |
| T2526N756C-DDW  | T2526S756C-DDW  |